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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 22376.2-2008

**Adhesives -- Methods of preparing bulk specimens -- Part 2:
Elevated-temperature-curing one-part systems**

胶粘剂 本体试样的制备方法 第2部分：热固化单组份体系

(English Translation)

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Foreword

GB/T 22376 "Adhesive bulk sample preparation method" is divided into two parts.

--- Part 1. Two-component system;

--- Part 2. Hot curing one-component system.

Preparation of 2000 "adhesive body specimens. This section GB/T 22376 Part 2, this part identical with ISO 15166-2 Part 2. Hot curing one-component systems "(in English).

This section is equivalent translation ISO 15166-2:2000, part of the normative references replaced by the national standards with international standards, the reference standard Associate content with international standards there is no difference.

For ease of use, this standard to the following editorial changes.

a) "this International Standard" be replaced by "this standard";

b) Remove the preface to the international standards.

This part is proposed by the China Petroleum and Chemical Industry Association.

The adhesive part of the National Standardization Technical Committee (SAC/TC185) centralized.

This section is drafted. Shanghai Rubber Products Research Institute, Beijing Tianshan new materials technology limited liability company, Foshan Nanhai tyrants of chemical Co., Ltd., Shanghai Kangda Chemical Co., Ltd.

Introduction

In the design adhesive joints, it is necessary to know the exact value of the mechanical properties of structural adhesives, it is possible to calculate the stress load in the joint distribution and to determine the adhesive damage allowable value. Use adhesive joints in

the form of a sample to test the performance of the above-mentioned method is not ideal. Because the standard Layer thickness on the sample size of the strain and the thickness value is generally small (typically 1 Scope this section GB/T 22376 specifies the preparation of bulk adhesive sample.

The method is suitable for the preparation of heat-curable, one-component adhesives, such as epoxy resins. Does not apply to the release of gas or solvent evaporation by Cured adhesive.

2 Normative references

The following documents contain provisions which, through reference GB/T 22376 in this section constitute provisions of this section. For dated reference documents Member, all subsequent amendments (not including errata content) or revisions do not apply to this section, however, encouraged to reach under this section Parties to research agreement to use the latest versions of these documents. For undated reference documents, the latest versions apply to this section.

GB/T 11997 Preparation and use of plastic multipurpose test specimens (ISO 3167:1993, MOD) ISO 2818:1994 --- plastic machining method for preparing a sample

3.1 Overview

Mold should be composed of two plates separated by a frame. For non-free-flowing adhesive should be used U-frame or continuous box (see Figure 1).

3.2 Tablet

Preparation of 5mm thick metal plate using at least said two plates. This facilitates heat transfer adhesive curing process, but also to avoid sample preparation Process due to an external force caused by deformation of the metal plate.

Copper and brass is a good conductor of heat, often used as plate material. However, when the use of certain copper corrosive ingredients, should be Alternative metal material.

We should not stick to the metal plate to ensure that the adhesive cured.

NOTE: This is achieved by a layer of material attached to the surface of a low surface energy material to achieve, such as polytetrafluoroethylene (PTFE) film, or brushing or spraying on the surface of the mold Release agent (PTFE spraying other surfaces adjacent to guard against contamination).

a) for non-free-flowing adhesive U-shaped frame b) for the continuous free-flowing adhesive frame Examples of suitable model 1 when preparing fast room temperature curing and curing process will produce a lot of heat adhesive bulk sample, since this procedure may cause adhesive Performance change, so mold metal plate should be designed to pass

cooling water structures.

GB/T 22376.2-2008/ISO 15166-2:2000